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ABSTRACT

In order in a simple and economical manner to enable an alignment of substrates, an apparatus is provided for the alignment of disk-shaped substrates, especially semiconductor wafers, with an alignment detection unit, at least one first support for receiving the substrate, which forms a plane that inclined relative to the horizontal, an abutment against which the substrate is movable due to the incline, and a rotation device for the rotation of the substrate. Furthermore provided is a method for the alignment of disk-shaped substrates, especially semiconductor wafers, with the following method steps: Moving the substrate into a position that is inclined relative to the horizontal, in which the substrate is received on a support that forms a plane that is tilted relative to the horizontal, and due to the incline rests against at least one abutment; rotating the substrate into a prescribed rotated position; and monitoring the rotated position with a detection unit.

Figure 10